

RELIABILITY REPORT
FOR
MAX17126BETM+
PLASTIC ENCAPSULATED DEVICES

May 24, 2012

MAXIM INTEGRATED PRODUCTS

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Conclusion

The MAX17126BETM+ successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim's quality and reliability standards.

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I. Device Description

A. General

The MAX17126B generates all the supply rails for thin-film transistor liquid-crystal display (TFT LCD) TV panels operating from a regulated 12V input. They include a step-down and a step-up regulator, a positive and a negative charge pump, an operational amplifier, a high-accuracy high-voltage gamma reference, and a high-voltage switch control block. The MAX17126B can operate from input voltages from 8V to 16.5V and is optimized for an LCD TV panel running directly from 12V supplies. The step-up and step-down switching regulators feature internal power MOSFETs and high-frequency operation allowing the use of small inductors and capacitors, resulting in a compact solution. The step-up regulator provides TFT source driver supply voltage, while the step-down regulator provides the system with logic supply voltage. Both regulators use fixed-frequency current-mode control architectures, providing fast load-transient response and easy compensation. A current-limit function for internal switches and output-fault shutdown protects the step-up and step-down power supplies against fault conditions. The MAX17126B provides soft-start functions to limit inrush current during startup. In addition, the MAX17126B integrates a control block that can drive an external p-channel MOSFET to sequence power to source drivers. The positive and negative charge-pump regulators provide TFT gate-driver supply voltages. Both output voltages can be adjusted with external resistive voltage-dividers. A logic-controlled, high-voltage switch block allows the manipulation of the positive gate-driver supply. The MAX17126B includes one high-current operational amplifier designed to drive the LCD back-plane (VCOM). The amplifier features high output current ($\pm 200\text{mA}$), fast slew rate ($45\text{V}/\mu\text{s}$), wide bandwidth (20MHz), and rail-to-rail outputs. Also featured in the MAX17126B is a high-accuracy, high-voltage adjustable reference for gamma correction. The MAX17126B is available in a small (7mm x 7mm), ultra-thin (0.8mm), 48-pin TQFN package and operate over the -40°C to $+85^{\circ}\text{C}$ temperature range.

II. Manufacturing Information

A. Description/Function:	Multi-Output Power Supplies with VCOM Amplifier and High-Voltage Gamma Reference for LCD TVs
B. Process:	S4
C. Number of Device Transistors:	
D. Fabrication Location:	Taiwan
E. Assembly Location:	Taiwan
F. Date of Initial Production:	September 15, 2011

III. Packaging Information

A. Package Type:	48L TQFN
B. Lead Frame:	Copper
C. Lead Finish:	100% matte Tin
D. Die Attach:	Conductive
E. Bondwire:	Au (1 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-9000-3605 / A
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	1
J. Single Layer Theta Ja:	36°C/W
K. Single Layer Theta Jc:	1°C/W
L. Multi Layer Theta Ja:	25°C/W
M. Multi Layer Theta Jc:	1°C/W

IV. Die Information

A. Dimensions:	mils
B. Passivation:	Si ₃ N ₄ /SiO ₂ (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Al/0.5%Cu with Ti/TiN Barrier
D. Backside Metallization:	None
E. Minimum Metal Width:	Metal1 = 0.5 / Metal2 = 0.6 / Metal3 = 0.6 microns (as drawn)
F. Minimum Metal Spacing:	Metal1 = 0.45 / Metal2 = 0.5 / Metal3 = 0.6 microns (as drawn)
G. Bondpad Dimensions:	
H. Isolation Dielectric:	SiO ₂
I. Die Separation Method:	Wafer Saw

V. Quality Assurance Information

A. Quality Assurance Contacts:	Richard Aburano (Manager, Reliability Engineering) Don Lipps (Manager, Reliability Engineering) Bryan Preeshl (Vice President of QA)
B. Outgoing Inspection Level:	0.1% for all electrical parameters guaranteed by the Datasheet. 0.1% For all Visual Defects.
C. Observed Outgoing Defect Rate:	< 50 ppm
D. Sampling Plan:	Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the biased (static) life test are shown in Table 1. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{\text{MTTF}} = \frac{1.83}{1000 \times 4340 \times 202 \times 2} \quad (\text{Chi square value for MTTF upper limit})$$

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$$\lambda = 1.0 \times 10^{-9}$$

$$\lambda = 1.0 \text{ F.I.T. (60\% confidence level @ 25°C)}$$

The following failure rate represents data collected from Maxim's reliability monitor program. Maxim performs quarterly life test monitors on its processes. This data is published in the Reliability Report found at <http://www.maxim-ic.com/qa/reliability/monitor>. Cumulative monitor data for the S4 Process results in a FIT Rate of 0.49 @ 25C and 8.49 @ 55C (0.8 eV, 60% UCL)

B. E.S.D. and Latch-Up Testing (lot TURWB3179B D/C 1036)

The PF58 die type has been found to have all pins able to withstand a HBM transient pulse of +/-2000V per JEDEC JESD22-A114. Latch-Up testing has shown that this device withstands a current of +/-100mA and overvoltage per JEDEC JESD78.

Table 1
Reliability Evaluation Test Results

MAX17126BETM+

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES	COMMENTS
Static Life Test (Note 1)	Ta = 135°C	DC Parameters	47	0	TURZEA282AB, D/C 1052
	Biased	& functionality	80	0	FURWCQ001C, D/C 1119
	Time = 1000 hrs.		75	0	FURWCQ002C, D/C 1119

Note 1: Life Test Data may represent plastic DIP qualification lots.